



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-19
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9916	K8BV*UR61ADV	A	BO2A	2016-01-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	5500.00	mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	19.6x10.3x4.5	8	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	K8BV*UR61ADV					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	10.440	mg	supplier	die	Silicon (Si)	7440-21-3		9.481	mg	908142	1724
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.646	mg	61877	117
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.074	mg	7088	13
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	96	0
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	96	0
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.030	mg	2874	5
Die				supplier	metallization	Platinum (Pt)	7440-06-4		0.040	mg	3831	7
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.103	mg	9866	19
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	479	1
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	1341	3
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.042	mg	4023	8
Die				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	287	1
Leadframe	Copper & its alloys	4259.807	mg	supplier	alloy	Copper (Cu)	7440-50-8		4251.583	mg	998069	773015
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.958	mg	460	356
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		3.576	mg	839	650
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		2.690	mg	631	489
Die attach		6.740	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.572	mg	975074	1195
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.101	mg	14985	18
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.067	mg	9941	12
Bonding wire				supplier	wire	Aluminium (Al)	7429-90-5		5.444	mg	1000000	990
encapsulation		1196.578	mg	supplier	mold compound	Silica, vitreous	60676-86-0		861.537	mg	720001	156643
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		203.418	mg	170000	36985
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		86.154	mg	72000	15664
encapsulation				supplier	mold compound	Brominated epoxy resin	40039-93-8		17.948	mg	14999	3263
encapsulation				supplier	mold compound	Carbon black	1333-86-4		3.590	mg	3000	653
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		23.931	mg	20000	4351
connections coating	Solder	20.990	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		20.990	mg	1000000	3816